App. Serial No.: 10/017,458
Atty. Docket No.: 0011-051

IN THE CLAIMS

Please amend the claims to read as follows:

1. (currently amended) A method for creating a dummy metal fill pattern near functional circuitry, comprising:

[[a.]] creating a margin area around the functional circuitry;

selecting a dummy metal fill pattern of alternative functional circuitry;

[[b.]] trimming [[a]] the dummy metal fill pattern to the margin area to create a trimmed fill pattern; and

[[c.]] overlaying said trimmed fill pattern and the functional circuitry [[; and]]

~~wherein the dummy fill pattern is an example of an alternative functional circuitry~~.

2. (currently amended) The method for creating a dummy metal fill pattern of claim 1, and further including:

removing excess metal ~~between step b and step c~~ from the dummy metal fill pattern.

3. (original) The method for creating a dummy metal fill pattern of claim 2, wherein:

the excess metal is at least one metal sliver.

4. (currently amended) The method for creating a dummy metal fill pattern of claim 3, wherein:

the metal sliver is a thin strip of metal created when the margin area is removed from the dummy metal fill pattern.

Claim 5 (canceled)

6. (previously amended) The method for creating a dummy metal fill pattern of claim 1, wherein:

the alternative functional circuitry is selected to be alike to that near the functional circuitry.

App. Serial No.: 10/017,458
Atty. Docket No.: 0011-051

7. (previously amended) The method for creating a dummy metal fill pattern of claim 1, wherein:

the alternative functional circuitry is a selected portion of functional circuitry from a metal layer on which the dummy metal fill pattern is to be used.

8. (original) The method for creating a dummy metal fill pattern of claim 1, wherein:

the dummy metal fill pattern is created on a metal layer of an LCOS array.

9. (original) The method for creating a dummy metal fill pattern of claim 1, wherein:

the dummy metal fill pattern is created on a layer under a mirror layer of an LCOS array.

10. (original) The method for creating a dummy metal fill pattern of claim 1, wherein:

the dummy metal fill pattern is created on a layer of a reflective LCOS array.

11. (canceled)

12. (canceled)

13. (original) The method for creating a dummy metal fill pattern of claim 1, wherein:

said margin area is created by growing the area of the functional circuitry.

14. (withdrawn) A metal fill pattern comprising:

a first circuitry pattern;

a margin area around said first circuitry pattern; and

a second circuitry pattern, wherein:

said second circuitry pattern is trimmed to avoid the margin area.

15. (withdrawn) The metal fill pattern of claim 13, wherein:

the first circuitry pattern is functional circuitry.

16. (withdrawn) The metal fill pattern of claim 14, wherein:
the second circuitry pattern is electrically non-functional.

17. (withdrawn) The metal fill pattern of claim 14, wherein:
the second circuitry pattern is selected to be a functional circuitry pattern located near the first circuitry pattern on a metal layer.

18. (withdrawn) The metal fill pattern of claim 14, wherein:
said first circuitry pattern and said second circuitry pattern are patterns on a metal layer of a reflective LCOS array.

19. (withdrawn) The metal fill pattern of claim 14, wherein:
said first circuitry pattern and said second circuitry pattern are patterns on a single metal layer of a reflective LCOS array.

20. (withdrawn) The metal fill pattern of claim 14, wherein:
at least one is artifact removed from the second circuitry pattern.

21. (withdrawn) The metal fill pattern of claim 20, wherein:
the artifact includes a metal sliver remaining after said second circuitry pattern is trimmed.

22. (withdrawn) The metal fill pattern of claim 14, wherein:
the second circuitry pattern is a functional circuitry pattern which is used as dummy fill metal.

23. (original) A method for providing dummy fill in a LCOS array, comprising:
selecting a metal fill pattern from functional circuitry on a layer of the array; and
filling an unfilled area with the metal fill pattern.

24. (original) The method for providing dummy fill of claim 23, and further including:
filling a partially filled area with a portion of the metal fill pattern.